

## Supplementary Information

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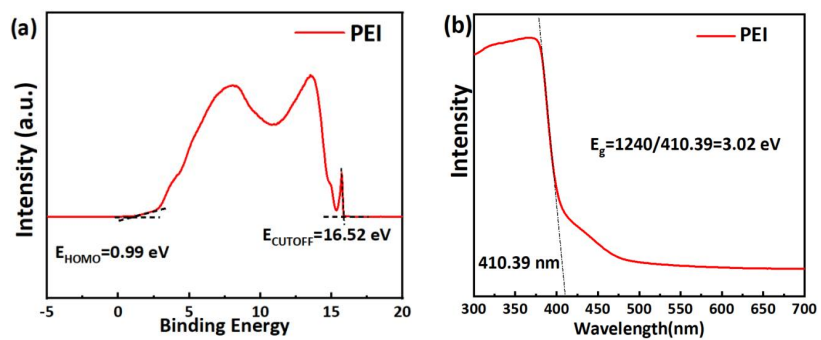


Figure S1 (a) UPS measurements in the secondary electron cutoff and HOMO regions of PEI. (b) UV-vis absorption spectra of PEI.

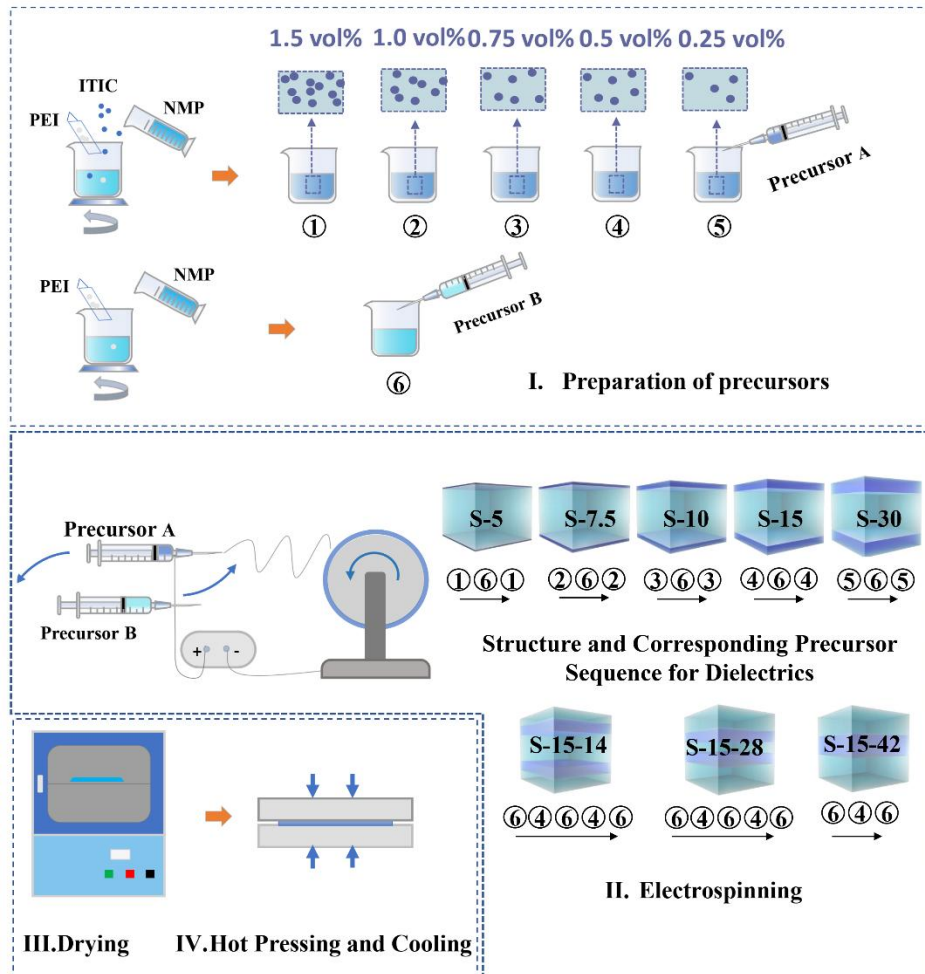


Figure. S2 Schematic of the preparation for trap-introduced PEI composite dielectrics.

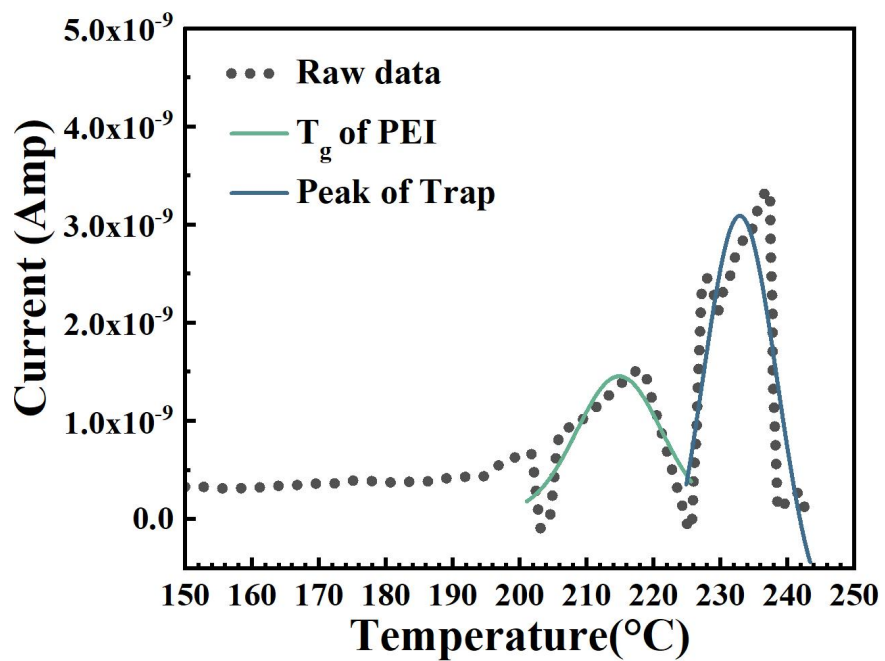


Figure S3. TSDC of S-15-28.

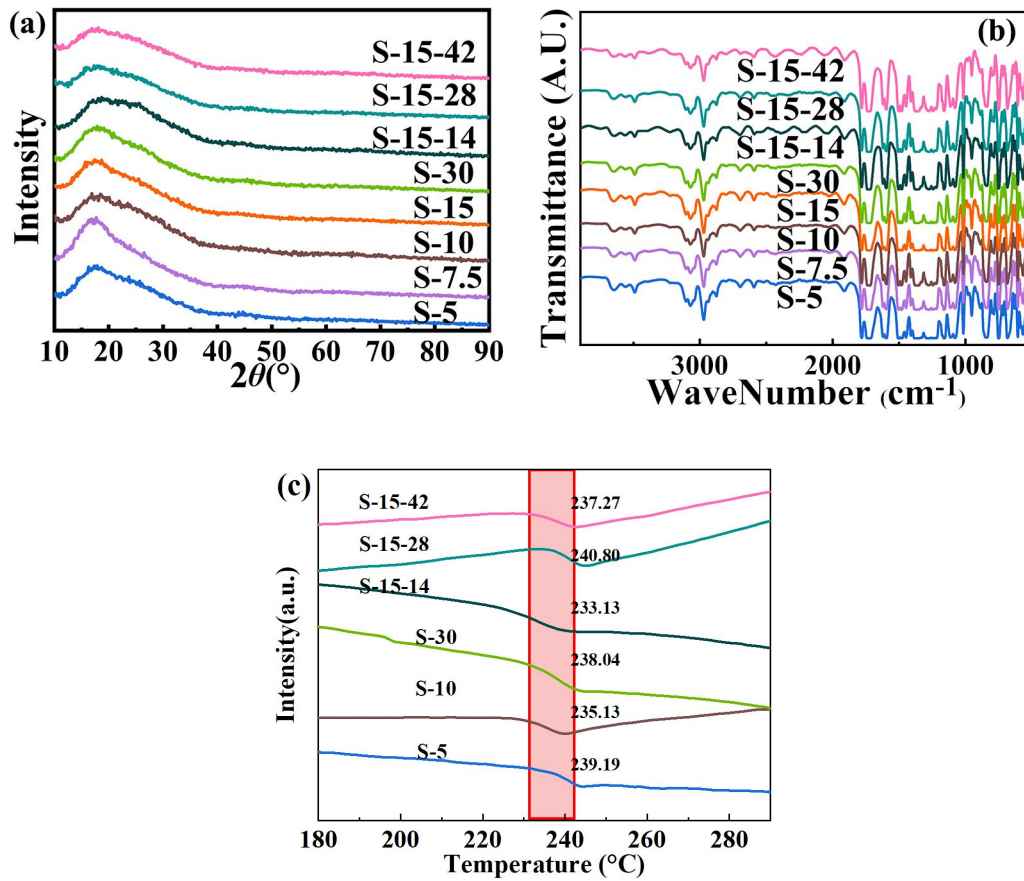


Figure S4. (a) XRD pattern and (b) FTIR spectrum (c) DSC curves for composite dielectrics.

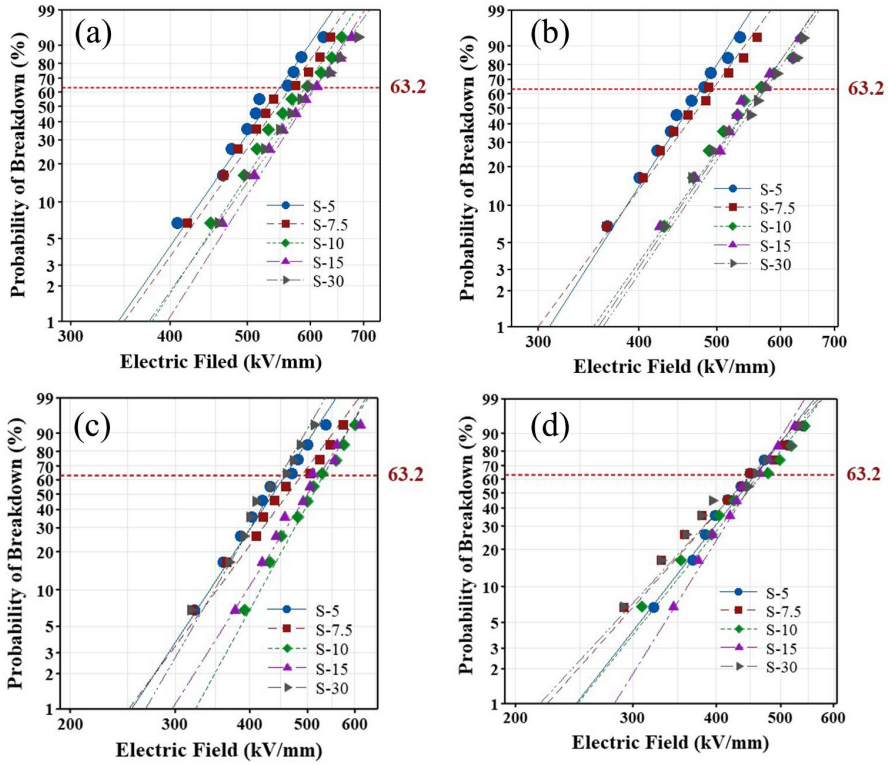


Figure S5. Weibull distribution of breakdown strength at (a) 20°C, (b) 100°C, (c) 150°C and (d) 180°C for composite dielectrics with different trap densities.

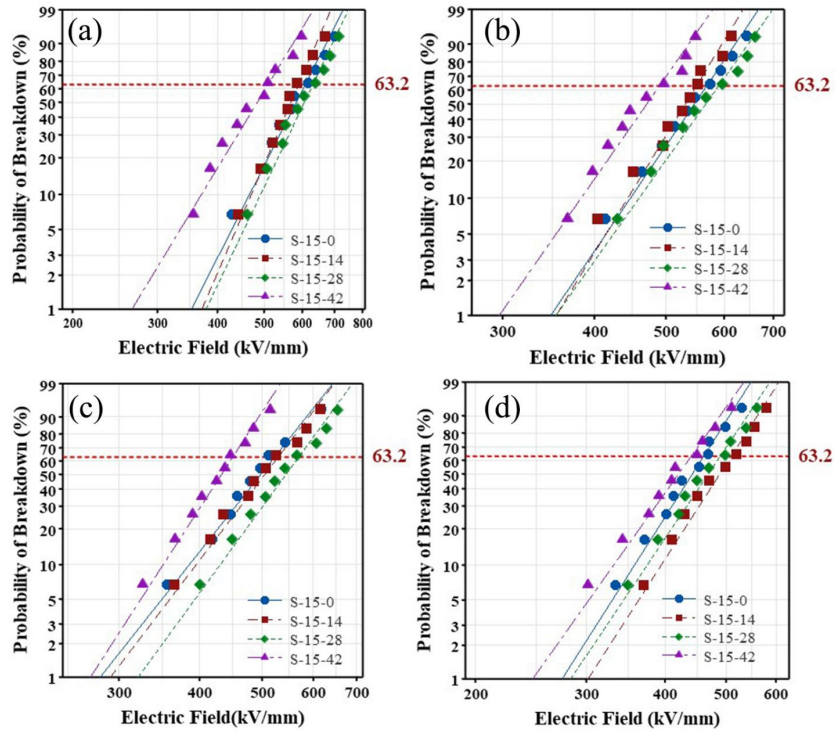


Figure S6. Weibull distribution of breakdown strength at (a) 20°C, (b) 100°C, (c) 150°C and (d) 180°C for composite dielectrics with different trap layer.

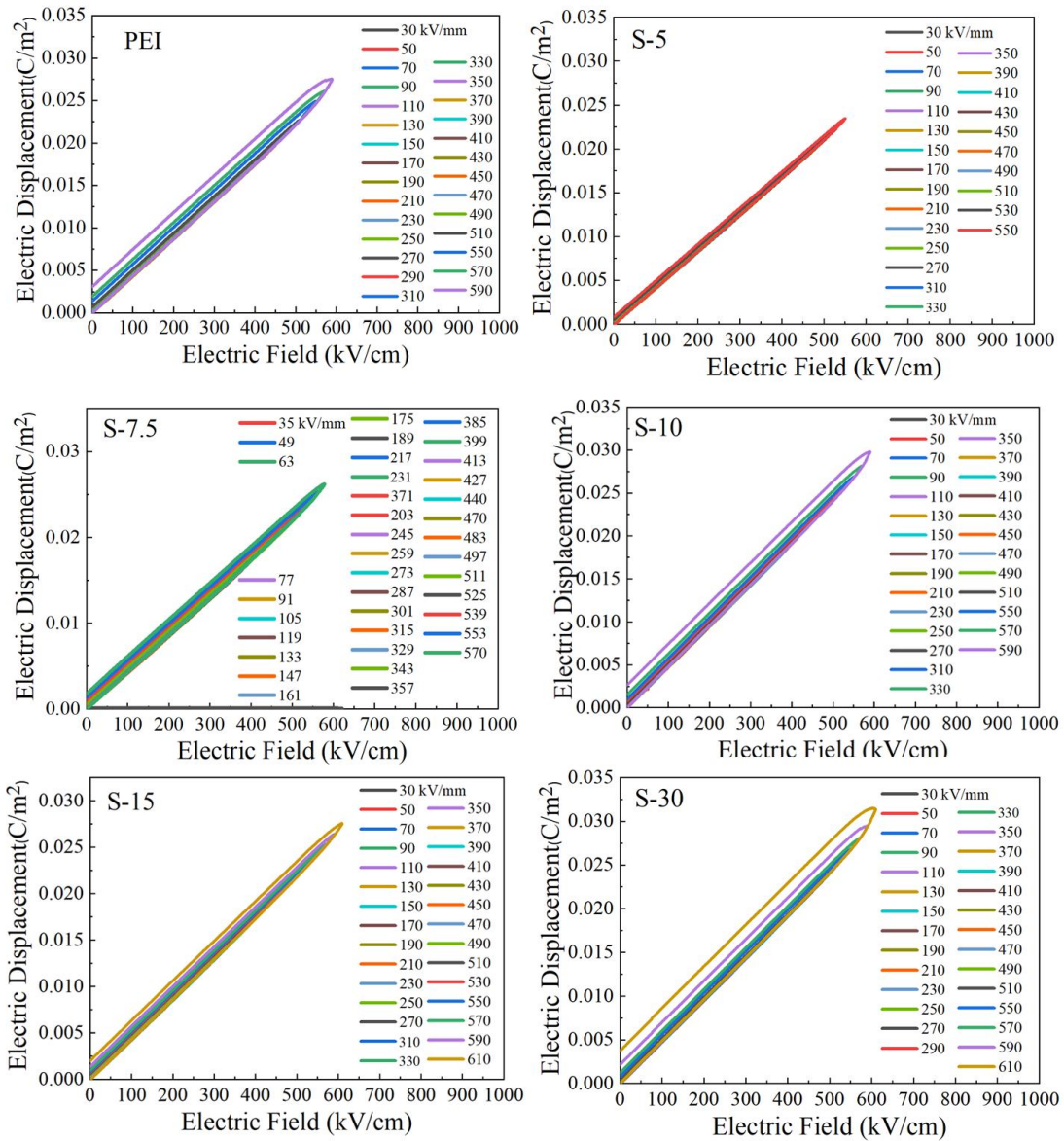


Figure S7. *D-E* loops for composite dielectrics with different trap density at 20°C.



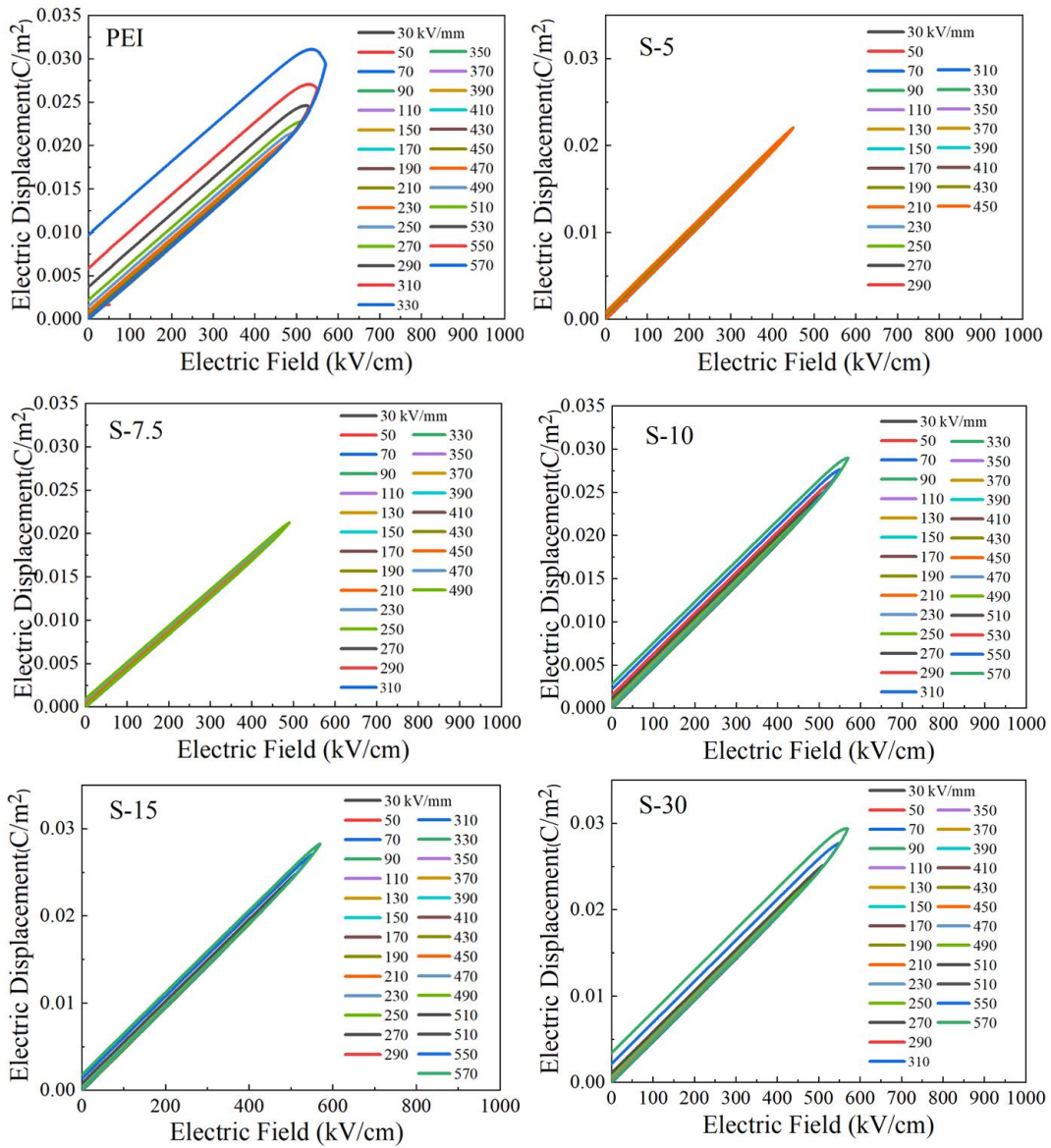


Figure S8. *D-E* loops for composite dielectrics with different trap density at 100°C



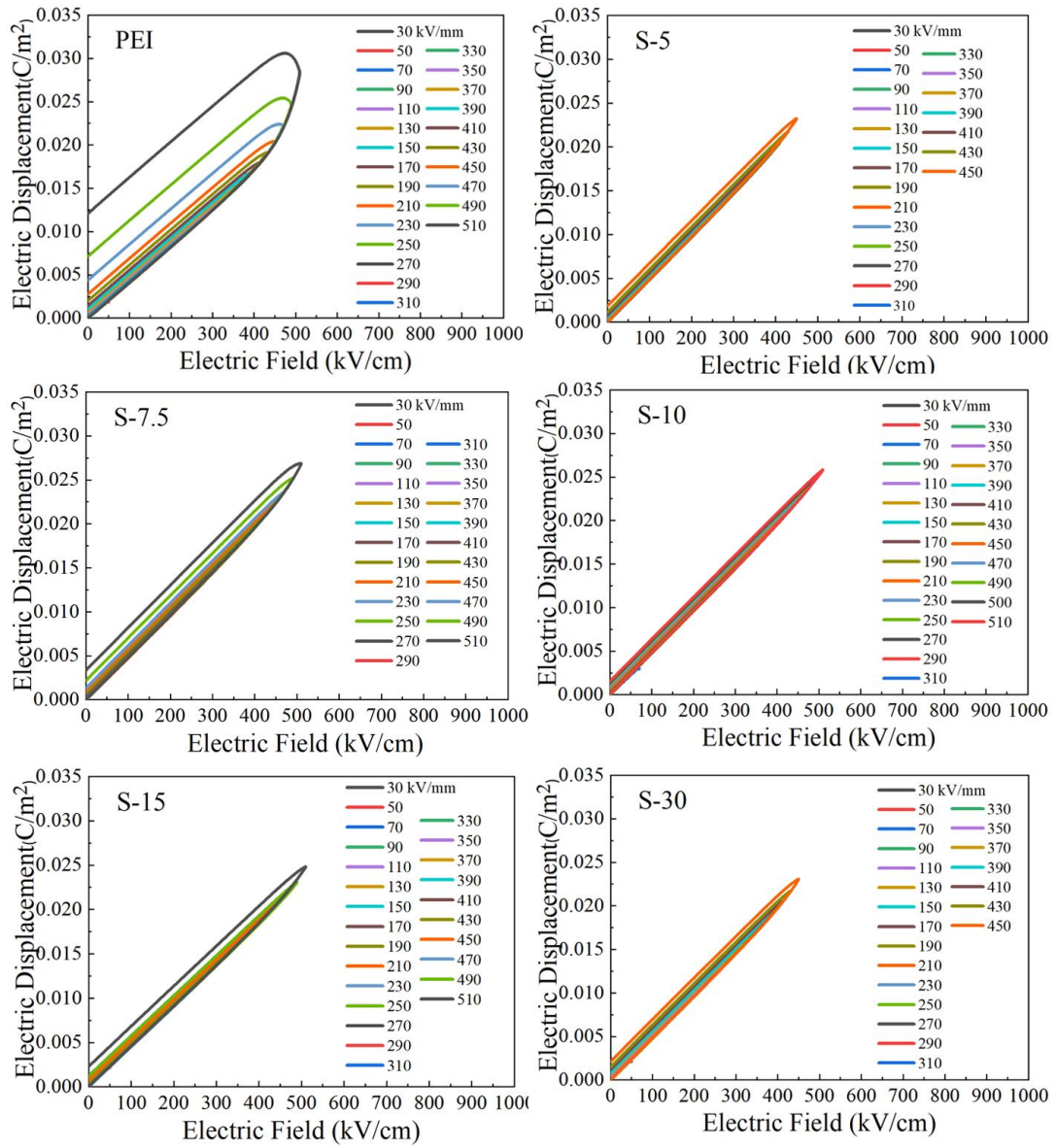


Figure S9. *D-E* loops for composite dielectrics with different trap density at 150°C

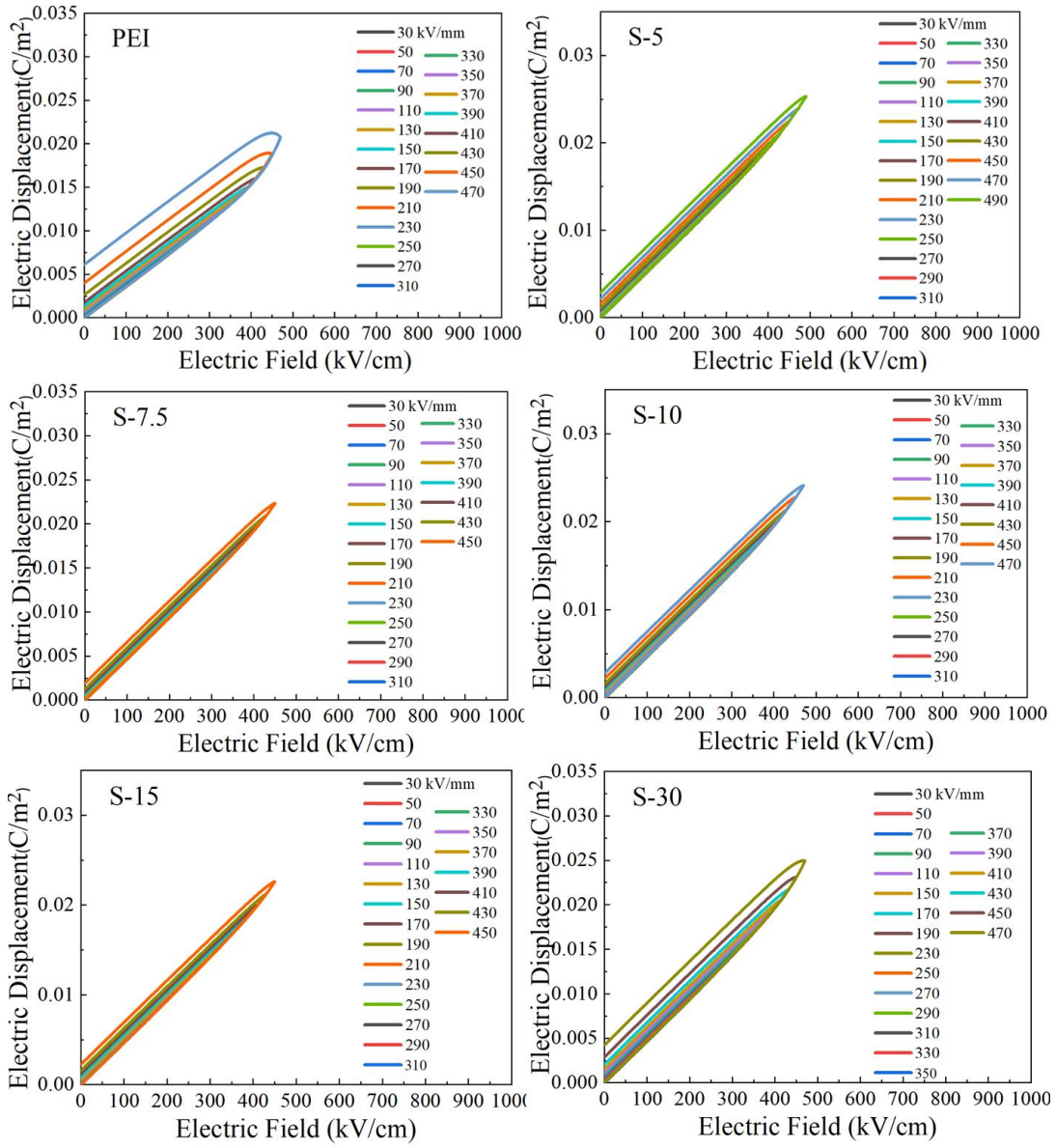


Figure S10 *D-E* loops for composite dielectrics with different trap density at 180°C

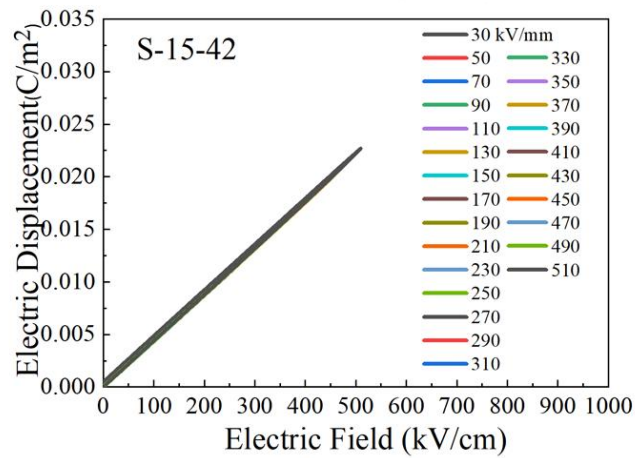
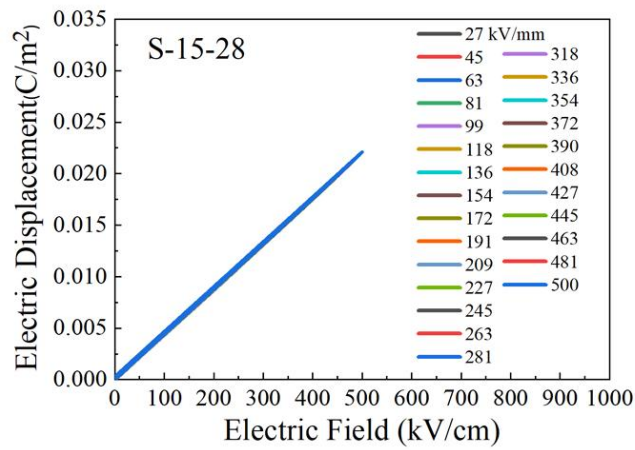
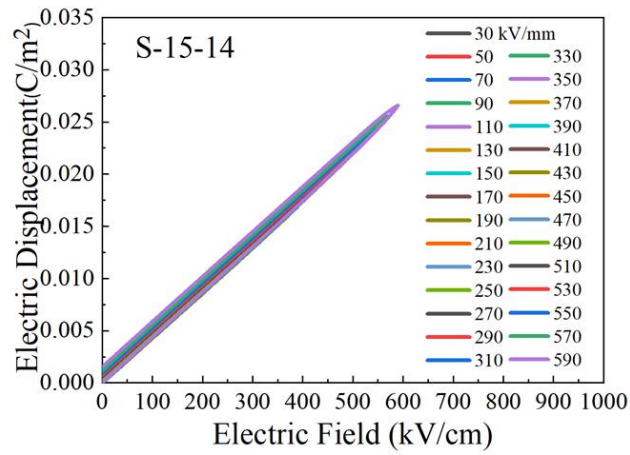


Figure S11 *D-E* loops for composite dielectrics with different trap layer locations at 20°C

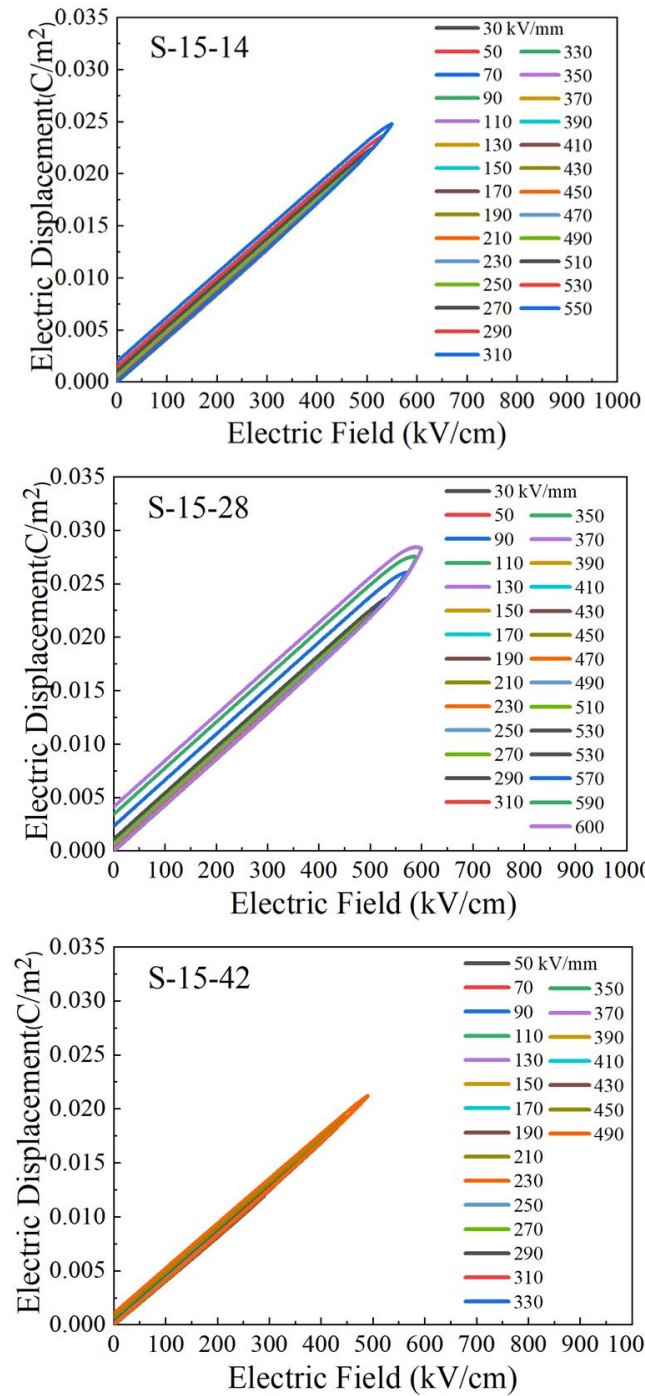


Figure S12 *D-E* loops for composite dielectrics with different trap layer locations at 100°C

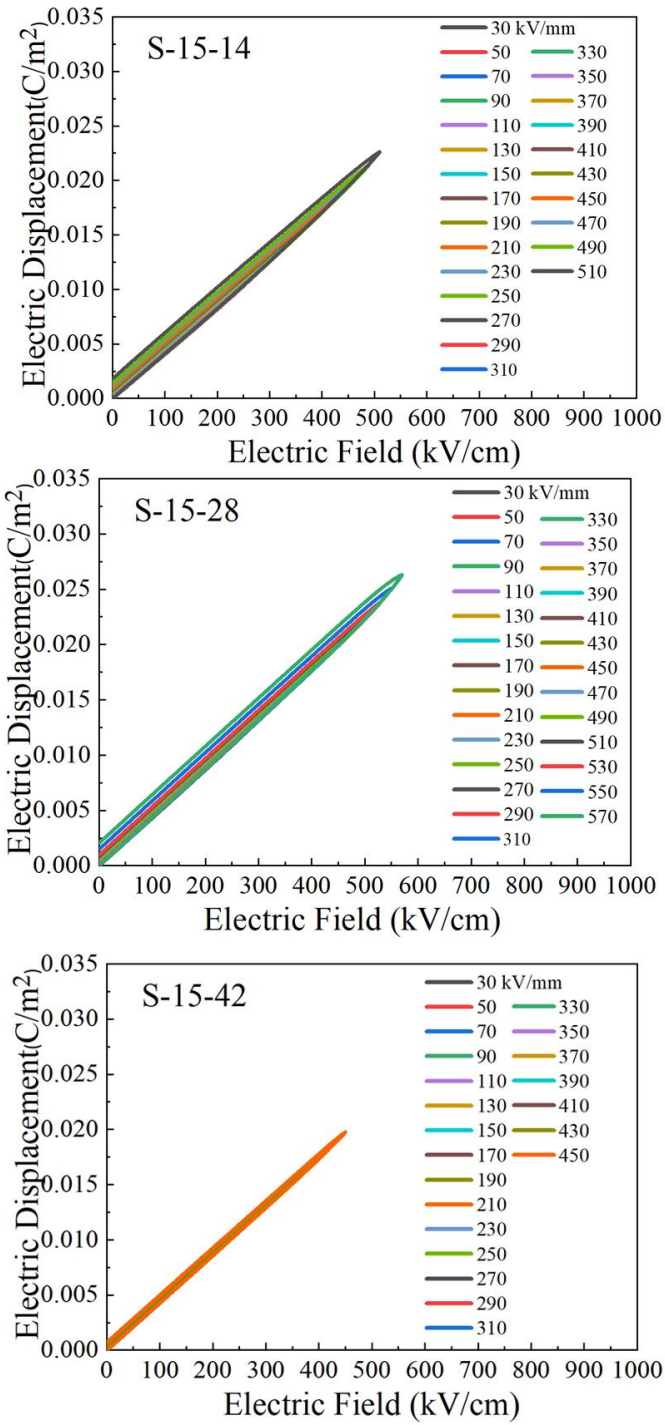


Figure S13 *D-E* loops for composite dielectrics with different trap layer locations at 150°C



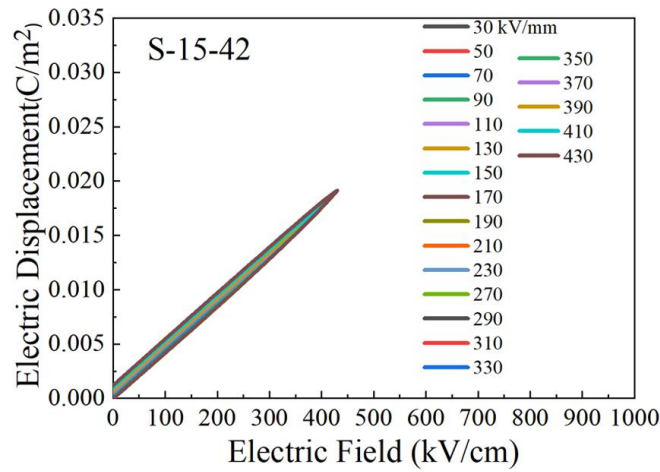
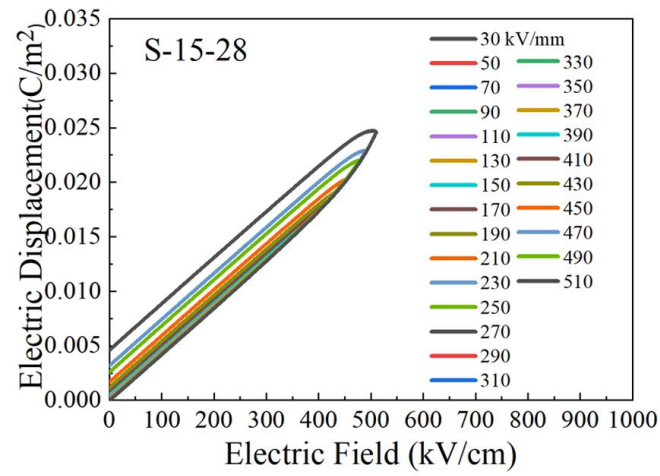
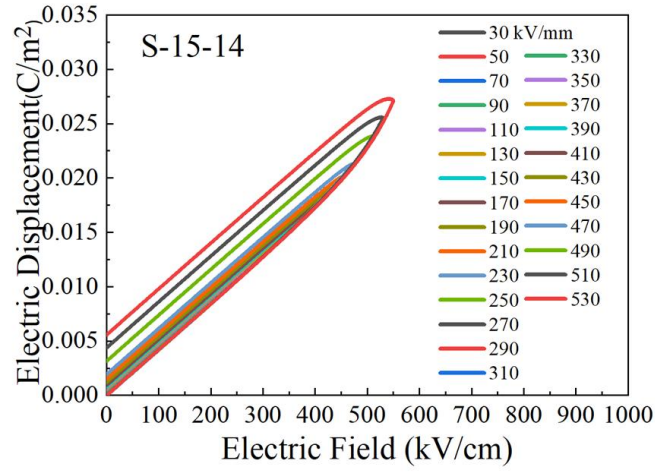


Figure S14 *D-E* loops for composite dielectrics with different trap layer locations at 180°C

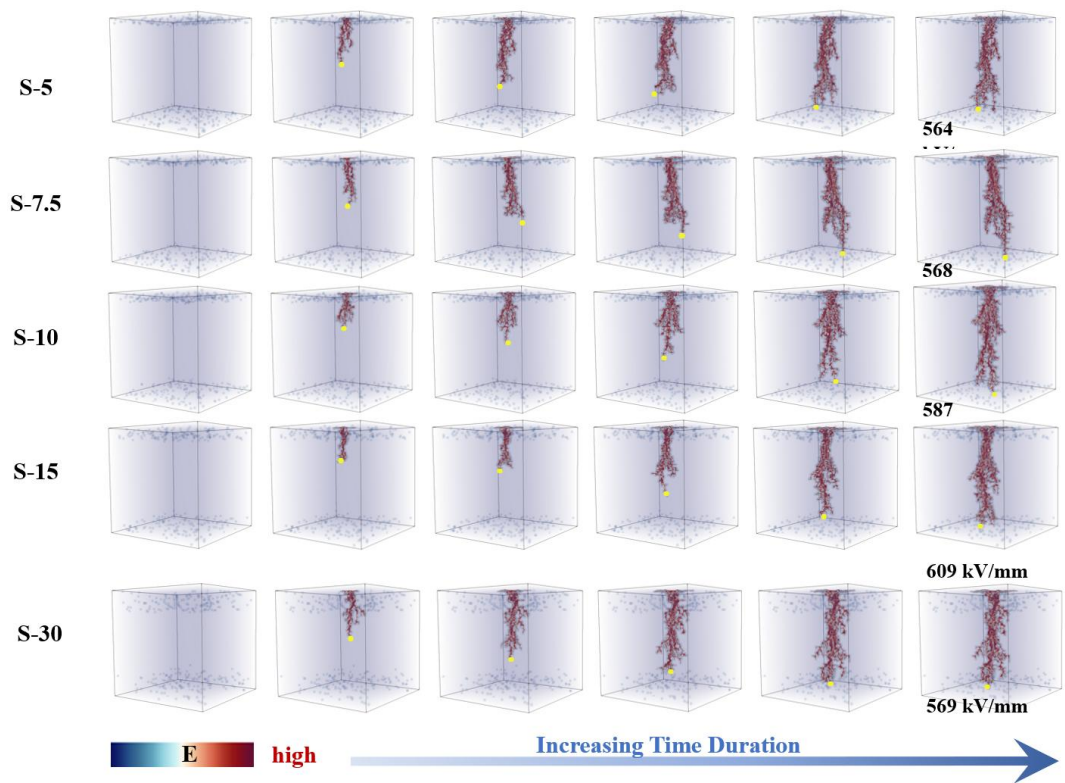


Figure S15 Phase-field simulation of breakdown process of composite dielectric with different trap densities at room temperature



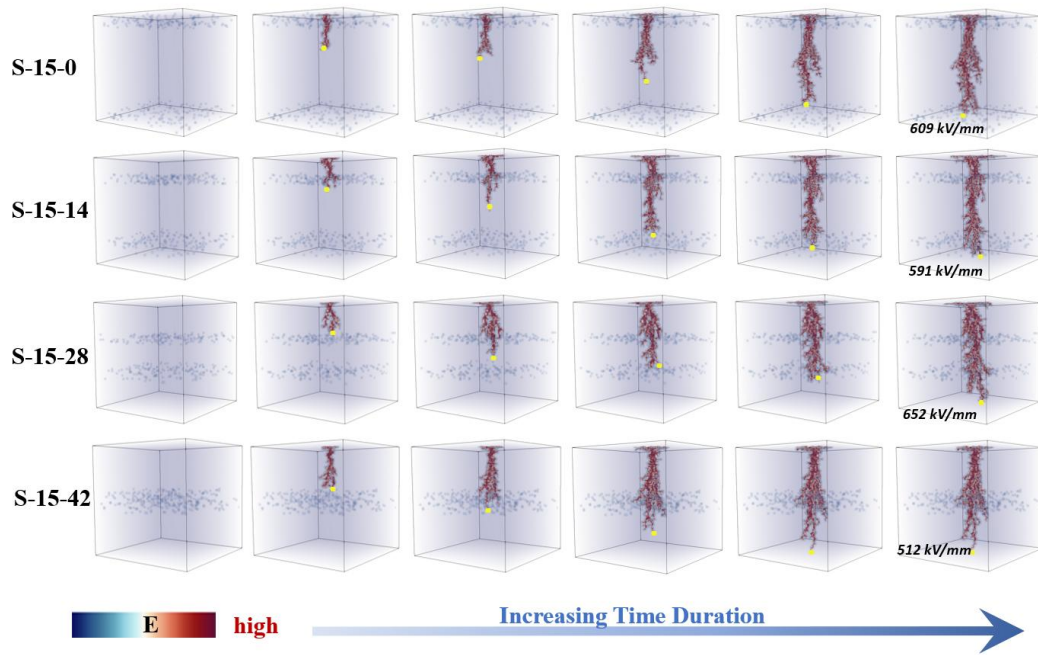


Figure S16 Phase-field simulation of breakdown process of composite dielectric with different trap layer locations at room temperature

## Supplementary Notes:

Stochastic breakdown Model:

The stochastic model proposed by Niemeyer et al. was improved to study the microstructure effect on the breakdown strength.<sup>[1,2]</sup> In this model, the breakdown probability of a local point is defined by

$$P(r) = \frac{E(r)^2}{E_b(r)^2} / \sum \frac{E(r)^2}{E_b(r)^2}$$

where  $E(r)$  is the electric field of a local point determined by the externally applied voltage and the microstructure, and  $E_b(r)$  is the corresponding intrinsic breakdown strength determined by the materials, and the summation in the denominator is the sum over all points that the local electric field exceeds the breakdown strength.<sup>[3]</sup> The local electric field distribution is obtained by solving the electric equilibrium equation using an spectral iterative perturbation method.<sup>[4]</sup> The material parameters used in the simulation are listed in Table S1.

**Table S1.** Material parameters used in the stochastic modeling of breakdown.

Material	Relative Dielectric Constant	Intrinsic Breakdown Strength (kV/mm)
PEI	3.2	450
Doped Particle	-1	600

### References

- [1] L. Niemeyer, L. Pietronero, H. J. Wiesmann, *Physical Review Letters* 1984, 52, 1033.
- [2] Y. Feng, J.-P. Xue, T.-D. Zhang, Q.-G. Chi, J.-L. Li, Q.-G. Chen, J.-J. Wang, L.-Q. Chen, *Energy Storage Materials* 2022, 44, 73.
- [3] D. Yue, Y. Feng, X. X. Liu, J. H. Yin, W. C. Zhang, H. Guo, B. Su, Q. Q. Lei, *Adv Sci* 2022, e2105773.
- [4] J. J. Wang, X. Q. Ma, Q. Li, J. Britson, L.-Q. Chen, *Acta Materialia* 2013, 61, 7591.